



VISHAY SUM70040E Power Mosfet N Channel User Guide

[Home](#) » [VISHAY](#) » VISHAY SUM70040E Power Mosfet N Channel User Guide 

Contents

- [1 VISHAY SUM70040E Power Mosfet N Channel](#)
- [2 Product Specifications](#)
- [3 Product Usage Instructions](#)
- [4 Frequently Asked Questions \(FAQ\)](#)
- [5 FEATURES](#)
- [6 APPLICATIONS](#)
- [7 PRODUCT SUMMARY](#)
- [8 ABSOLUTE MAXIMUM RATINGS \(TC = 25 °C, unless otherwise noted\)](#)
- [9 THERMAL RESISTANCE RATINGS](#)
- [10 SPECIFICATIONS \(TJ = 25 °C, unless otherwise noted\)](#)
- [11 TYPICAL CHARACTERISTICS \(TA = 25 °C, unless otherwise noted\)](#)
- [12 THERMAL RATINGS \(TA = 25 °C, unless otherwise noted\)](#)
- [13 Package Information](#)
- [14 RECOMMENDED MINIMUM PADS FOR D2PAK: 3-Lead](#)
- [15 Disclaimer](#)
- [16 Documents / Resources](#)
 - [16.1 References](#)



VISHAY SUM70040E Power Mosfet N Channel



Product Specifications

- **Brand:** Vishay Siliconix
- **Type:** N-Channel MOSFET
- **Drain-Source Voltage (VDS):** 100V
- **RDS(on) Max:** 0.0040 at VGS = 10V, 0.0046 at VGS = 7.5V
- **ID (A):** 120A
- **Gate Charge (Qg):** 76
- **Package Type:** TO-263

Product Usage Instructions

Features

- Lead (Pb)-free and halogen-free
- For compliance definitions, refer to www.vishay.com/doc?99912

Applications

Designed for N-Channel MOSFET applications.

Thermal Resistance Ratings

- Junction-to-Ambient (PCB Mount): 40°C/W
- Junction-to-Case (Drain): 0.4°C/W

Frequently Asked Questions (FAQ)

- **What is the maximum Drain-Source Voltage for this MOSFET?**
The maximum Drain-Source Voltage is 100V.
- **What is the Gate Charge for this MOSFET?**
The Gate Charge is 76.
- **What is the maximum Drain Current supported by this MOSFET?**

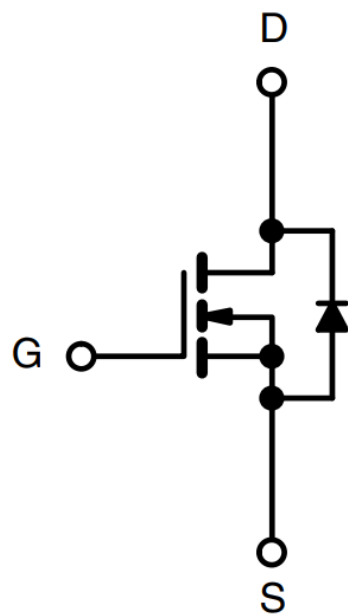
The maximum Drain Current is 120A.

FEATURES

- ThunderFET® power MOSFET
- Maximum 175 °C junction temperature
- 100 % Rg and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Power supply
Secondary synchronous rectification
- DC/DC converter
- Power tools
- Motor drive switch
- DC/AC inverter
- Battery management
- OR-ing



N-Channel MOSFET

PRODUCT SUMMARY

V _{DS} (V)	R _{DS(on)} (W) MAX.	I _D (A) d	Q _g (TYP.)
100	0.0040 at V _{GS} = 10 V	120	76
	0.0046 at V _{GS} = 7.5 V	120	

ABSOLUTE MAXIMUM RATINGS (TC = 25 °C, unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V _{DS}	100	V
Gate-Source Voltage		V _{GS}	± 20	
Continuous Drain Current (T _J = 150 °C)	T _C = 25 °C	I _D	120 d	A
	T _C = 70 °C		120 d	
Pulsed Drain Current (t = 100 μs)		I _{DM}	480	
Avalanche Current		I _{AS}	73	
Single Avalanche Energy a	L = 0.1 mH	E _{AS}	266	mJ
Maximum Power Dissipation a	T _C = 25 °C	P _D	375 b	W
	T _C = 125 °C		125 b	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +175	°C

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-Ambient (PCB Mount) c	R _{thJA}	40	°C/W
Junction-to-Case (Drain)	R _{thJC}	0.4	

Notes

- Duty cycle 1 %.
- See SOA curve for voltage derating.
- When mounted on 1" square PCB (FR4 material).
- Package limited.

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)

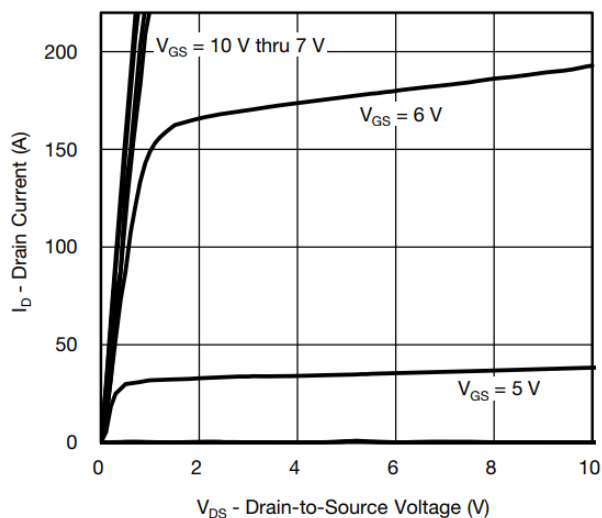
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	100	—	—	V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	2.5	—	4	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V	—	—	± 250	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V	—	—	1	μA
		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 125 °C	—	—	150	
		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 175 °C	—	—	5	mA
On-State Drain Current a	I _{D(on)}	V _{DS} ³ 10 V, V _{GS} = 10 V	120	—	—	A
Drain-Source On-State Resistance a	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A	—	0.0032	0.0040	W
		V _{GS} = 7.5 V, I _D = 15 A	—	0.0035	0.0046	
Forward Transconductance a	g _{fs}	V _{DS} = 15 V, I _D = 20 A	—	82	—	S
Dynamic b						
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 50 V, f = 1 MHz	—	5100	—	pF
Output Capacitance	C _{oss}		—	2025	—	
Reverse Transfer Capacitance	C _{rss}		—	165	—	
Total Gate Charge c	Q _g	V _{DS} = 50 V, V _{GS} = 10 V, I _D = 20 A	—	76	120	nC
Gate-Source Charge c	Q _{gs}		—	23	—	
Gate-Drain Charge c	Q _{gd}		—	17	—	
Gate Resistance	R _g	f = 1 MHz	0.6	3.3	6.6	W
Turn-On Delay Time c	t _{d(on)}	V _{DD} = 50 V, R _L = 5 W I _D @ 10 A, V _{GEN} = 10 V, R _g = 1 W	—	15	30	ns
Rise Time c	t _r		—	22	40	
Turn-Off Delay Time c	t _{d(off)}		—	55	100	
Fall Time c	t _f		—	15	30	
Drain-Source Body Diode Ratings and Characteristics b (T _C = 25 °C)						
Pulsed Current	ISM		—	—	480	A
Forward Voltage a	V _{SD}	I _F = 10 A, V _{GS} = 0 V	—	0.8	1.5	V

Notes

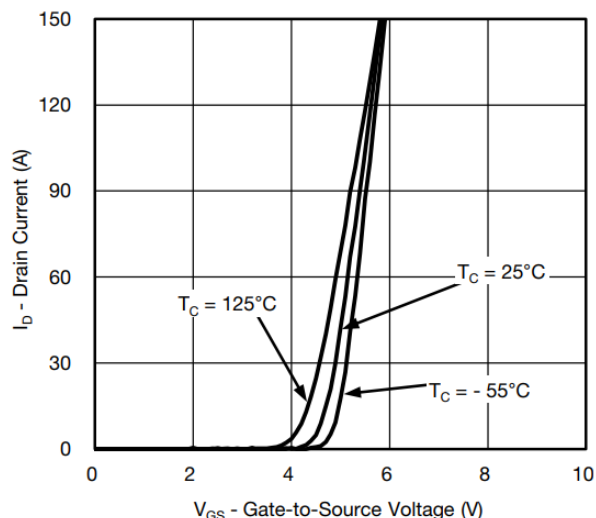
- Pulse test; pulse width 300 μ s, duty cycle 2 %.

- Guaranteed by design, not subject to production testing.
- Independent of operating temperature.

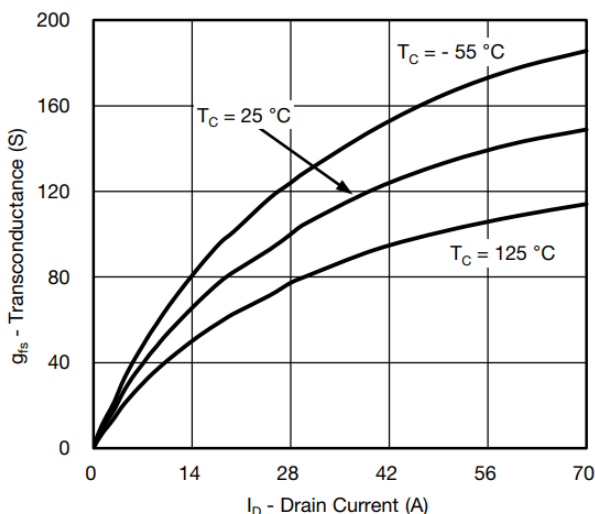
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



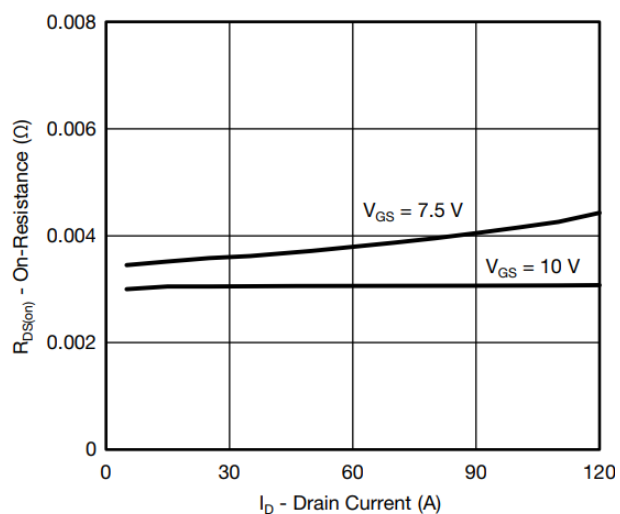
Output Characteristics



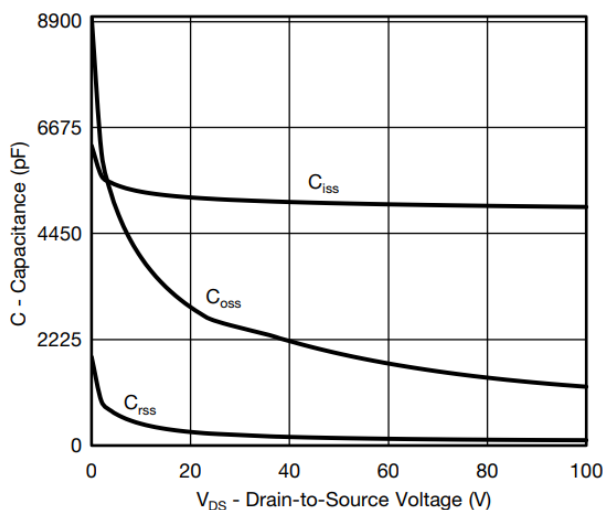
Transfer Characteristics



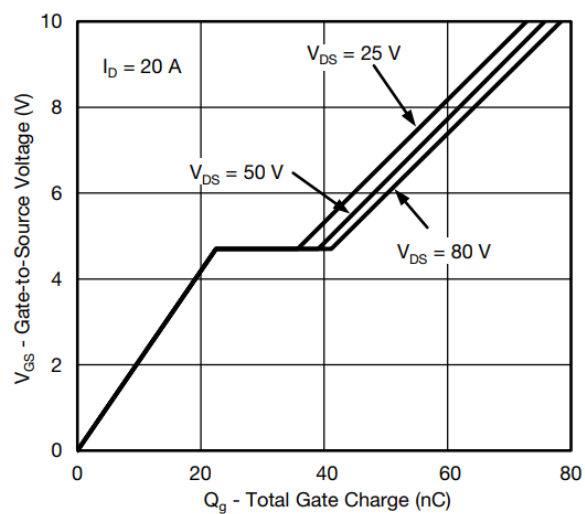
Transconductance



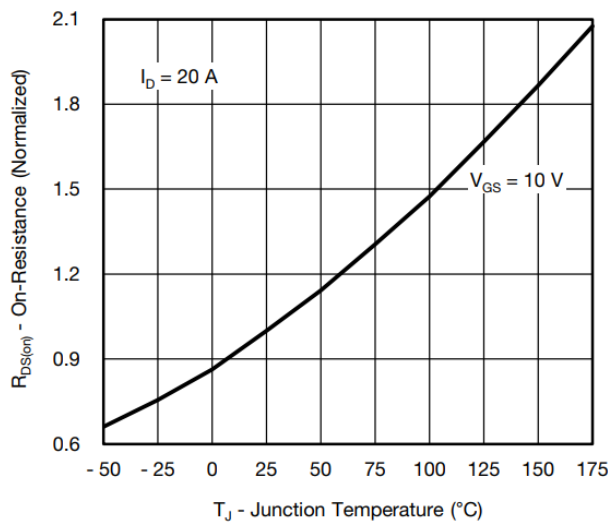
On-Resistance vs. Drain Current



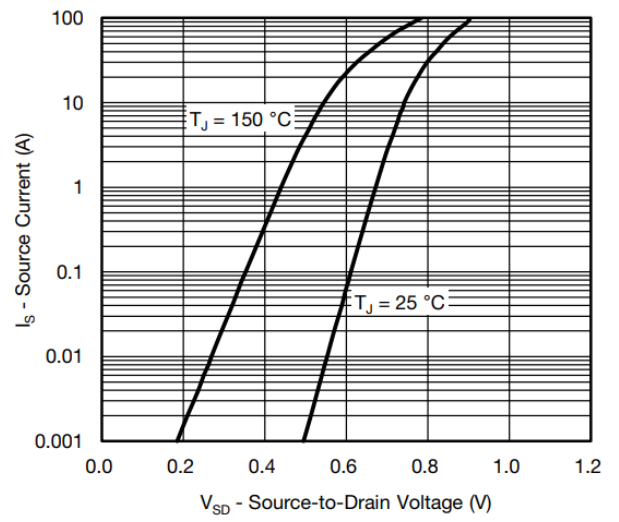
Capacitance



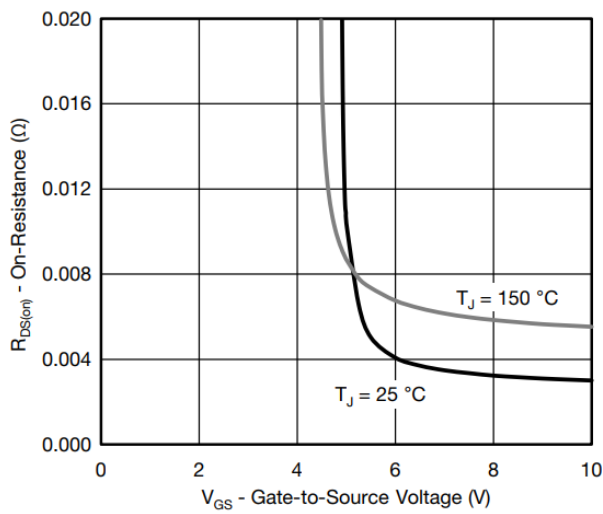
Gate Charge



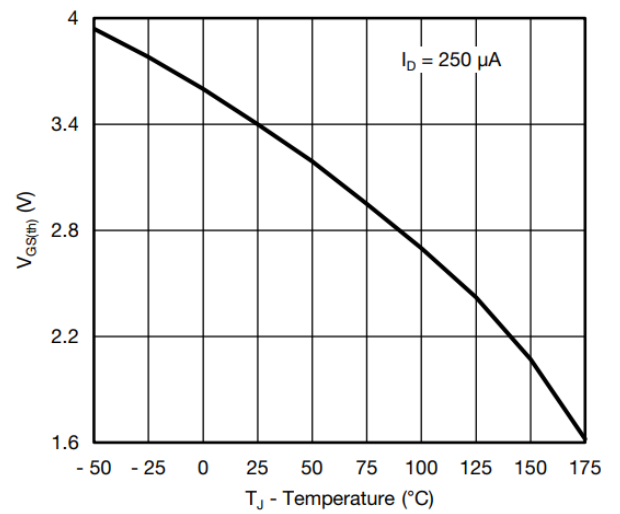
On-Resistance vs. Junction Temperature



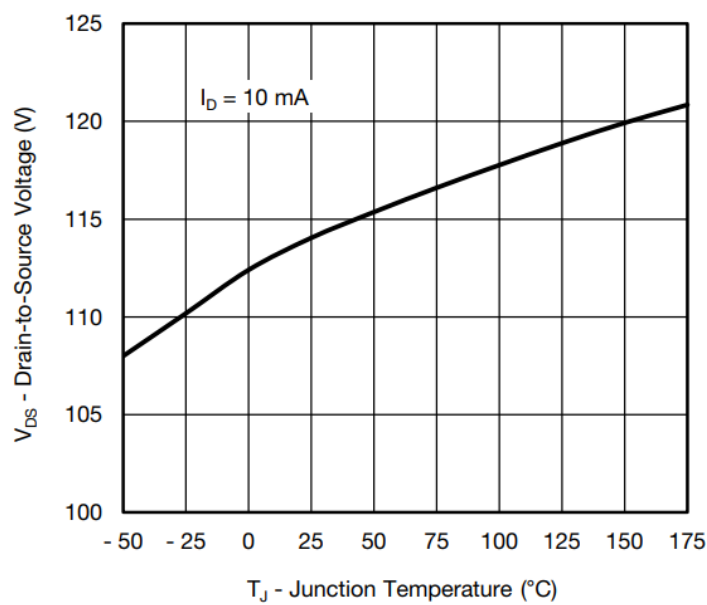
Source Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage

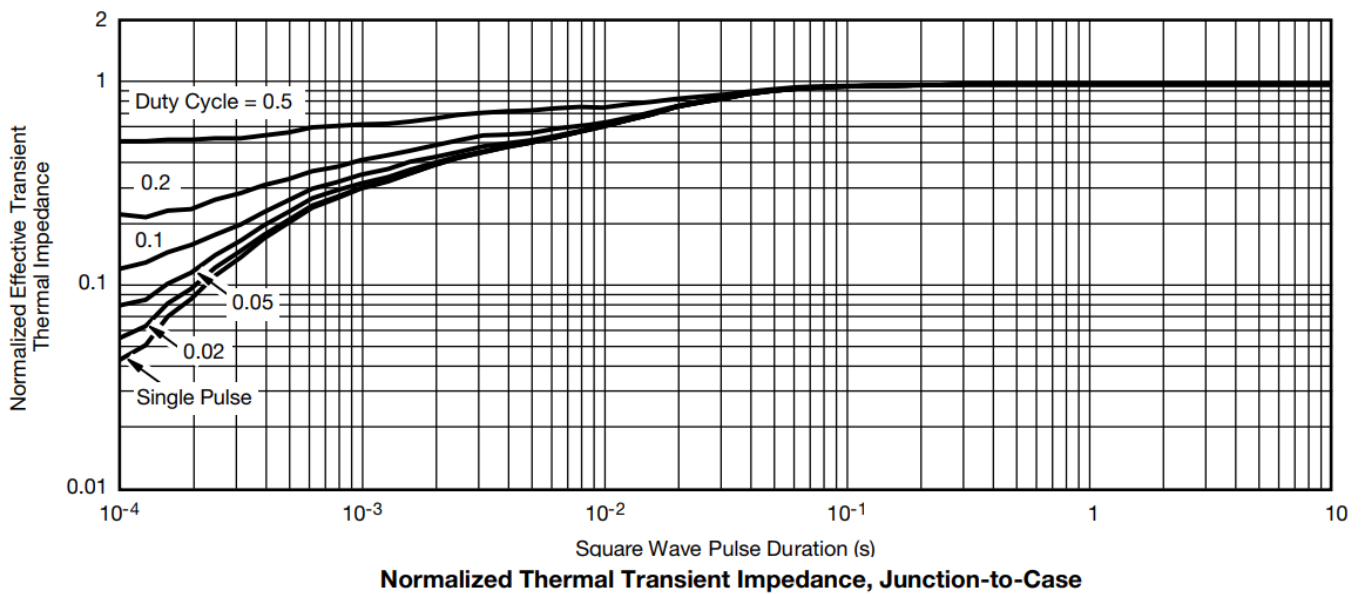
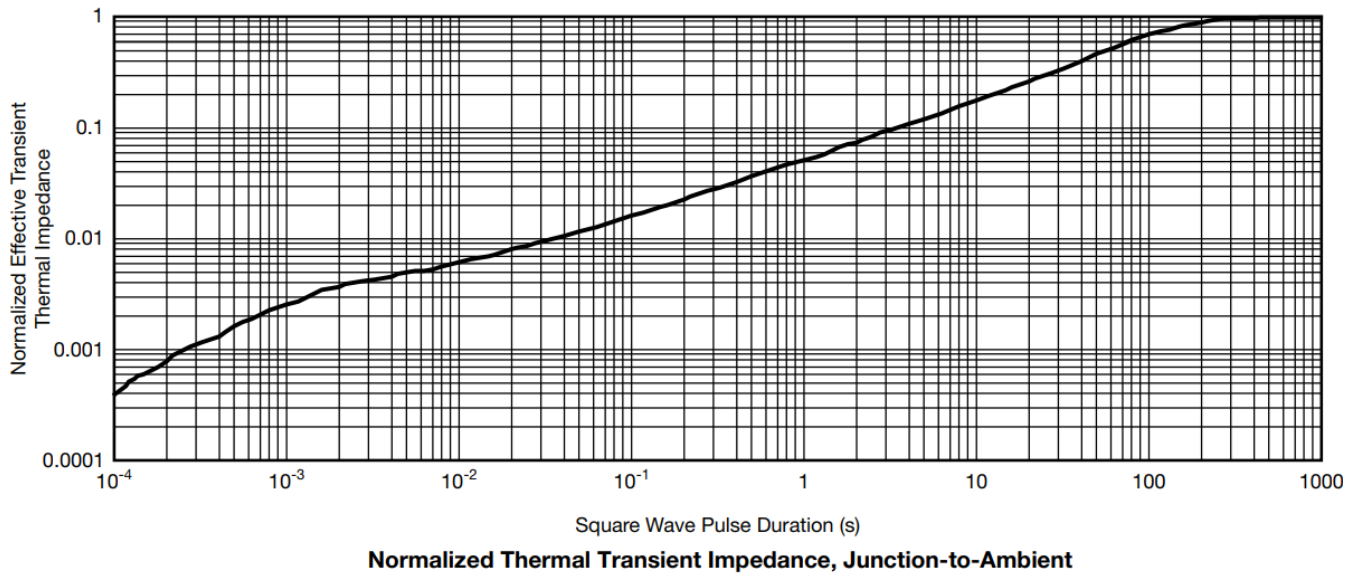
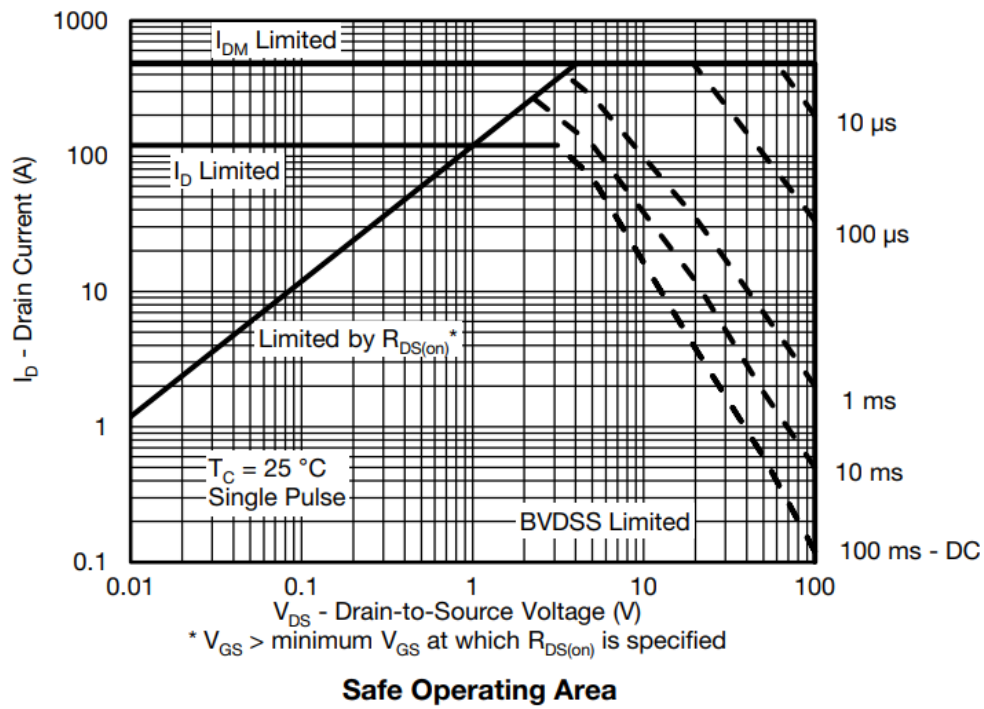


Threshold Voltage



Drain Source Breakdown vs. Junction Temperature

THERMAL RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



Note

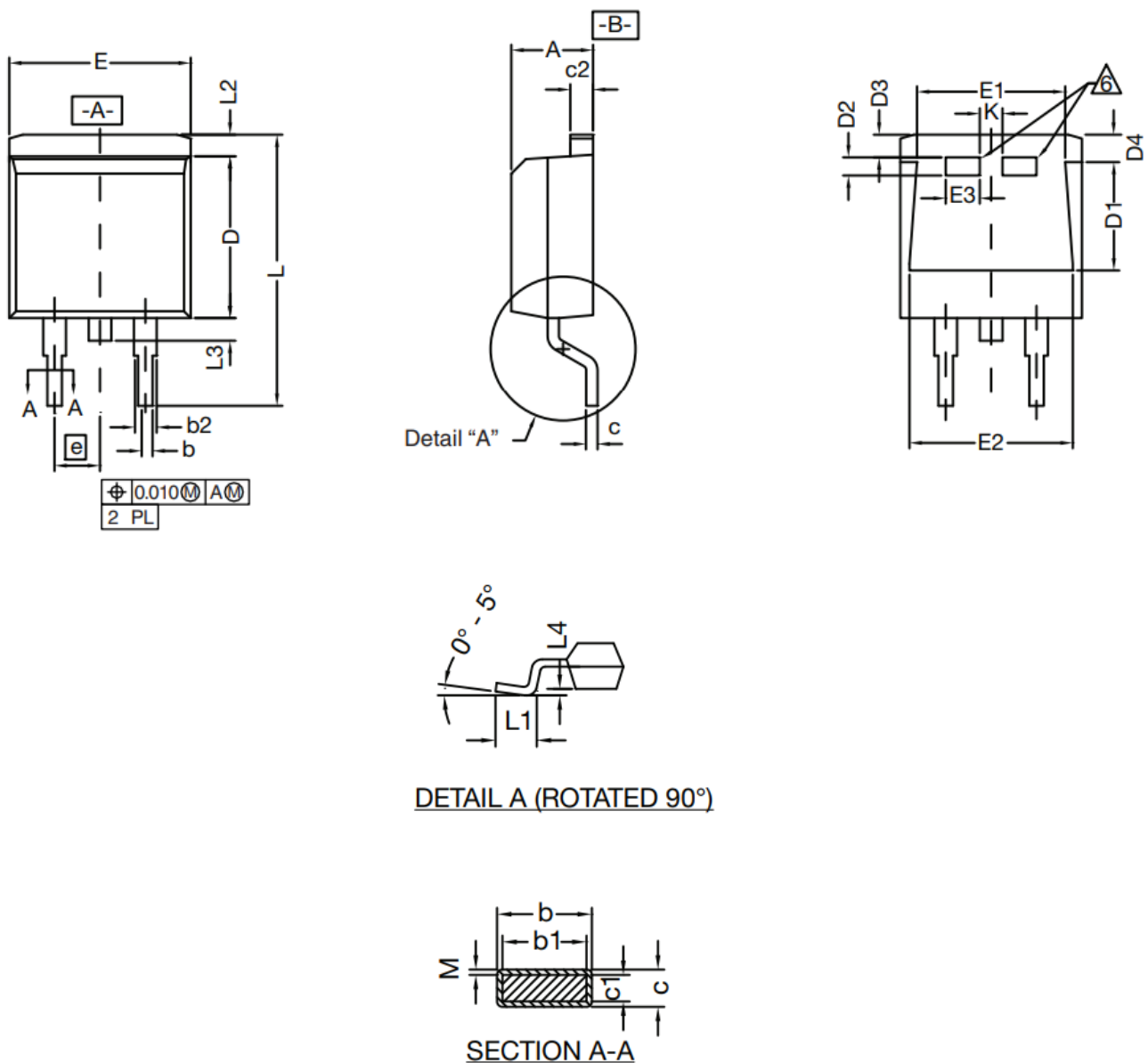
The characteristics shown in the two graphs

- Normalized Transient Thermal Impedance Junction to Ambient (25 °C)
- Normalized Transient Thermal Impedance Junction to Case (25 °C)

are given for general guidelines only to enable the user to get a “ball park” indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board – FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Package Information

TO-263 (D2PAK): 3-LEAD

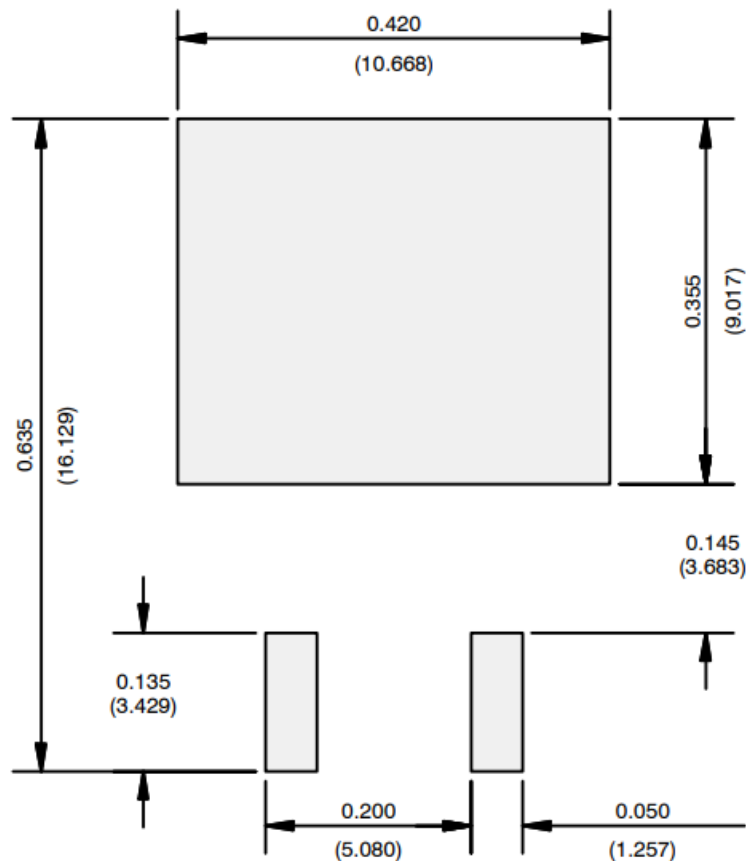


DIM.		INCHES		MILLIMETERS	
		MIN.	MAX.	MIN.	MAX.
A		0.160	0.190	4.064	4.826
b		0.020	0.039	0.508	0.990
b1		0.020	0.035	0.508	0.889
b2		0.045	0.055	1.143	1.397
c*	Thin lead	0.013	0.018	0.330	0.457
	Thick lead	0.023	0.028	0.584	0.711
c1	Thin lead	0.013	0.017	0.330	0.431
	Thick lead	0.023	0.027	0.584	0.685
c2		0.045	0.055	1.143	1.397
D		0.340	0.380	8.636	9.652
D1		0.220	0.240	5.588	6.096
D2		0.038	0.042	0.965	1.067
D3		0.045	0.055	1.143	1.397
D4		0.044	0.052	1.118	1.321
E		0.380	0.410	9.652	10.414
E1		0.245	—	6.223	—
E2		0.355	0.375	9.017	9.525
E3		0.072	0.078	1.829	1.981
e		0.100 BSC		2.54 BSC	
K		0.045	0.055	1.143	1.397
L		0.575	0.625	14.605	15.875
L1		0.090	0.110	2.286	2.794
L2		0.040	0.055	1.016	1.397
L3		0.050	0.070	1.270	1.778
L4		0.010 BSC		0.254 BSC	
M		—	0.002	—	0.050
ECN: T13-0707-Rev. K, 30-Sep-13 DWG: 5843					

Notes

1. Plane B includes maximum features of heat sink tab and plastic.
2. No more than 25 % of L1 can fall above seating plane by max. 8 mils.
3. Pin-to-pin coplanarity max. 4 mils.
4. Thin lead is for SUB, SYB.
Thick lead is for SUM, SYM, SQM.
5. Use inches as the primary measurement.
6. This feature is for thick lead.

RECOMMENDED MINIMUM PADS FOR D2PAK: 3-Lead



Recommended Minimum Pads
Dimensions in Inches/(mm)

Disclaimer

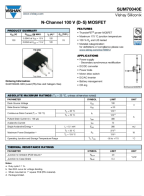
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References

-  [Vishay Intertechnology: Passives & Discrete Semiconductors](#)
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